Since the emergence of surface mounted devices a great deal of concern and discussion has gone into determining how to test boards crammed with these high-density devices. In 1990 these concerns resulted in ANSI/IEEE Standard 1149.1-1990, Standard Access Port and Boundary-Scan Architecture. This standard defines test logic that can be included on an integrated circuit to provide standardized approaches to testing the component itself or the interconnections between components on a printed circuit board. The standard also allows for observing or controlling the behavior of a component during its normal operation. The test logic allows test instructions and test data to be fed to a component, and upon execution of an instruction, allows the results to be read out and observed. All instructions, test data, and results are communicated in serial format.

The test logic defined by the standard consists of a chain of boundary-scan cells and test support logic, which are accessed through the TAP inputs (see Fig. 1). A boundary-scan cell is a shift-register stage that is connected between each input or output pin on an IC and the application logic to which each pin is normally connected (see Fig. 2). The scan cell has two states of operation. One state allows a sequence of bits representing data and instructions to be shifted (scanned-in) into a chain of scan cells, resulting in latching each cell to the desired value. The scan-in and scan-out lines shown in Fig. 2 carry the bits from one cell to another. The logic specified in the standard is designed so that the serial movement of instruction data is not apparent to the circuits whose operation is controlled by the instruction.

The other state of operation for the scan cells involves testing the application logic. The test operation involves either receiving test data from the application logic via the signal-in line and then latching the output, or shifting test data into the application logic via the signal-out line. The test logic is specified such that the movement of test data has no effect on the instruction present in the test circuitry.

After the test state is done the scan mode can be invoked again to shift out the latched test results for comparison with the expected results.

The clock, shift, and mode lines shown in Fig. 2 are controlled by the TAP signals (described below). The TAP lines are responsible for sending the proper signal sequences to control the scanning or testing states. In addition, the mode line is controlled according to the type of pin it is connected to (e.g., input, output, bidirectional, tristate, etc.).

The IEEE standard defines a minimum of three input connections and one output connection (see Fig 1). An optional fourth input (TRST*) provides for asynchronous initialization of the test logic circuitry defined in the standard.

![Fig. 1. A simplified block diagram of the test logic defined in ANSI/IEEE Standard 1149.1-1990 surrounding application logic.](image)
A scan chain is a shift-register path through a circuit which is typically placed there to improve testability. See "Overview of the Test Access Port" on page 56.

Test Clock. TCK is the test clock input that provides the clock for the test logic. This clock is provided so that scan cells surrounding the application logic can be controlled independently of system clocks. TCK allows shifting of test data concurrently with system operation (allowing online monitoring). It also ensures that test data can be moved to or from a chip without changing the state of the application logic.

Test Mode Select. TMS is the signal used by the TAP controller to control test operations. One use of TMS is to select whether the test circuitry is in the test state or the scan state. To guard against race conditions, the TMS signal like the TDI signal described below must be sampled on the rising edge of TCK.

Test Reset. The optional TRST* signal is included to allow for asynchronous reset of the TAP controller. The reset signal only affects the test logic and has no impact on the application logic.

Test I/O Lines. TDI and TDO are the test data input and output lines respectively. They provide for the serial movement of test data through the circuit. Data presented at TDI is clocked into the selected register on the rising edge of TCK, while output data appearing at TDO is clocked out on the falling edge of TCK. To simplify the operation of components that are compatible with the standard, data must be propagated from TDI to TDO without inversion.

Bibliography